

Rev.B Jun.-2022

DFN8 8-3L          650V GaN  
650V GaN Enhancement-mode Power Transistor in a DFN8x

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Transient Drain to Source Voltage <sup>1</sup>	$V_{TR\_DSS}$	725	V
Drain Current – Pulsed	$I_{DM}$	30	A
Gate-Source Voltage	$V_{GS}$	$\pm 18$	V
Continuous current, Drain Source $T_C=25$ <sup>2</sup>	$I_D$	6.5	A
Continuous current, Drain Source $T_C=100$ <sup>2</sup>		4.0	A
Power Dissipation	$P_D(T_C=25)$	21	W
Junction and Storage Temperature Range	$T_j, T_{stg}$	-55 to 150	
Thermal Resistance, Junction - Case	$R_{JC}$	5.9	/ W
Thermal Resistance, Junction - Ambient	$R_{JA}$	50	/ W

**Notes**

1. In off-state, spike duty cycle  $D \leq 0.01$ , spike duration  $\leq 1\mu s$
2. For increased stability at high current operation

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Breakdown Voltage	$V_{BLV_{DSS}}$	$V_{GS}=0V$	650			V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			15	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 18V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=500\mu A$	1.1	2.0	2.9	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=8V, I_D=5A$		250	330	m
		$V_{GS}=8V, I_D=5A, T_J=150$		500		

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Capacitance	$C_{iss}$	$V_{DS}=400V, V_{GS}=0V$ $f=1.0MHz$		760		pF
Output Capacitance	$C_{oss}$			16		

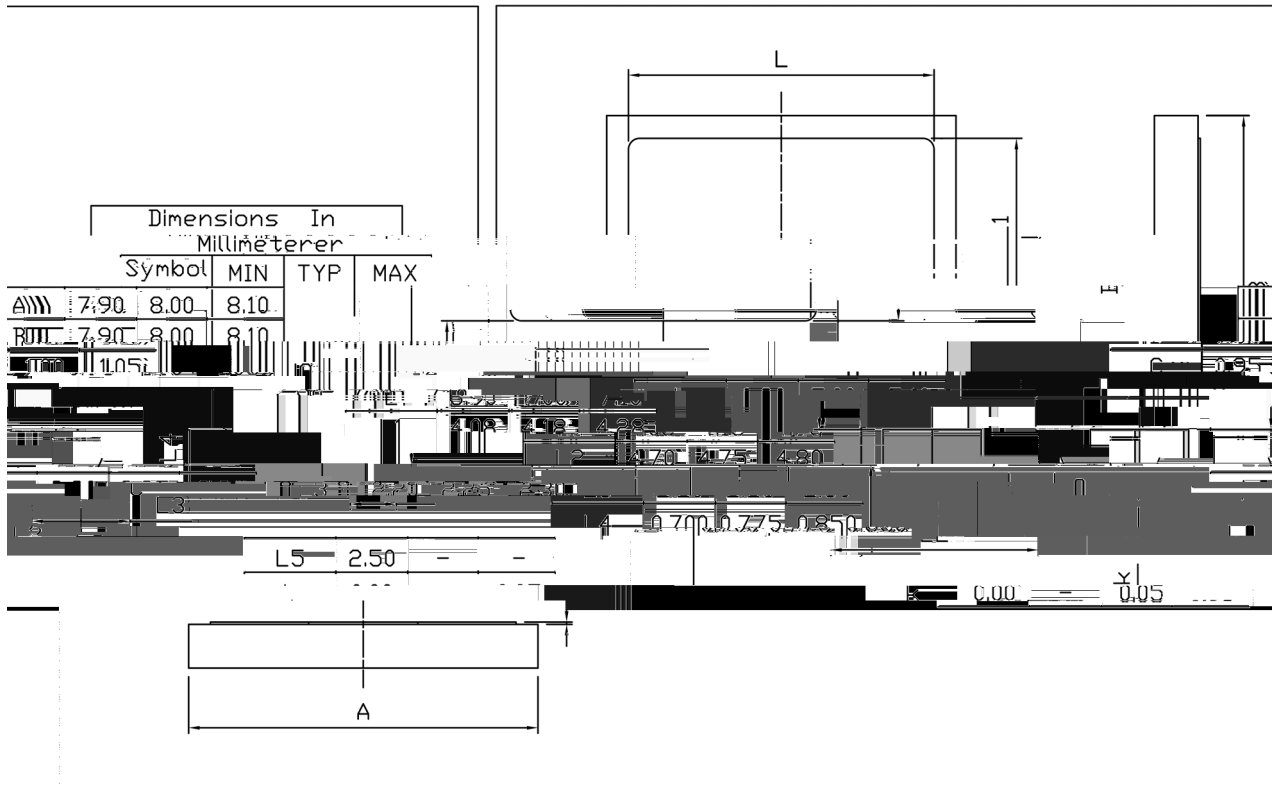
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=0\sim 8V,$ $V_{DS}=400V,$ $I_D=4A,$ $R_g=30$		20		ns
Turn-On Rise Time	$t_r$			4		
Turn-Off Delay Time	$t_{d(off)}$			52		
Turn-Off Fall Time	$t_f$			10		
Total Gate Charge	$Q_g$	$V_{GS}=0\sim 8V,$ $V_{DS}=400V,$ $I_D=4A$		9.5		nC
Gate Source Charge	$Q_{gs}$			2.7		
Gate Drain Charge	$Q_{gd}$			2.5		
Output Charge	$Q_{OSS}$	$V_{GS}=0V, V_{DS}=0\sim 400V,$		19		nC

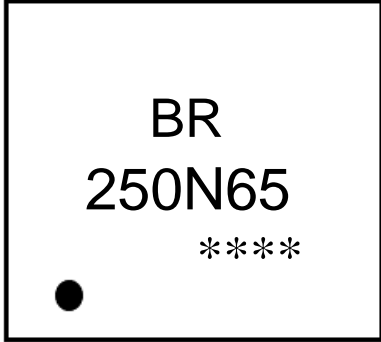
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{SD}$	$I_S=2A, V_{GS}=0V$		1.2		V
Pulsed Current, Reverse	$I_S$	$V_{GS} = 0V; T_C=100$ 25% duty cycle			4.0	A
Reverse Recovery Time	$t_{RR}$	$I_S=4A V_{DS}=400V$ $di/dt=1000A/us$		15		ns
Reverse Recovery Charge	$Q_{RR}$			22		nC

DFNR X2-3I

DFNR X2-3I

Unit:mm





BR  
250N65  
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250N65

Note

BR

Company Code

250N65

Product Type

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Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)


- |   |     |     |    |          |   |
|---|-----|-----|----|----------|---|
| 1 | 150 | 180 | 60 | 90sec;   | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245 | 5   | 5  | 0.5sec;  | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 |     |     | 2  | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |